

Global Wafer Level Package Market Growth (Status and Outlook) 2024-2030

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Abstracts

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According to this study, the global Wafer Level Package market size will reach US\$ 32390 million by 2030.

Following a strong growth of 26.2 percent in the year 2021, WSTS revised it down to a single digit growth for the worldwide semiconductor market in 2022 with a total size of US\$580 billion, up 4.4 percent. WSTS lowered growth estimation as inflation rises and end markets seeing weaker demand, especially those exposed to consumer spending. While some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.8 percent, Sensors with 16.3 percent, and Logic with 14.5 percent growth. Memory declined with 12.6 percent year over year. In 2022, all geographical regions showed double-digit growth except Asia Pacific. The largest region, Asia Pacific, declined 2.0 percent. Sales in the Americas were US\$142.1 billion, up 17.0% year-on-year, sales in Europe were US\$53.8 billion, up 12.6% year-on-year, and sales in Japan were US\$48.1 billion, up 10.0% year-on-year. However, sales in the largest Asia-Pacific region were US\$336.2 billion, down 2.0% year-on-year.

This report presents a comprehensive overview, market shares, and growth opportunities of Wafer Level Package market by product type, application, key players and key regions and countries.

Segmentation by product type:

3D Wire Bonding

3D TSV

Others

Segmentation by Application:

Consumer Electronics

Industrial

Automotive & Transport

IT & Telecommunication

Others

This report also splits the market by region:

United States

China

Europe

Other regions:

Japan

South Korea

Southeast Asia

Rest of world

The report also presents the market competition landscape and a corresponding detailed analysis of the major players in the market. The key players covered in this

report:

IASE

Amkor

Intel

Samsung

AT&S

Toshiba

JCET

Qualcomm

IBM

SK Hynix

UTAC

TSMC

China Wafer Level CSP

Interconnect Systems

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